TOSHIBA Photocoupler GaAlAs IRED + Photo IC

TLP705

Plasma Display Panel.
Industrial Inverter
IGBT/Power MOS FET Gate Drive

TLP705 consists of a GaAlAs light emitting diode and a integrated photodetector.

This unit is 6-lead SDIP package. TLP705 is 50% smaller than 8pin DIP and has suited the safety standard reinforced insulation class.

So mounting area in safety standard required equipment can be reduced. TLP705 is suitable for gate driving circuit of IGBT or power MOS FET. Especially TLP705 is capable of "direct" gate drive of lower Power IGBTs.

Peak output current : ±0.45 A (max)
 Operating frequency : 250kHz (max)
 Guaranteed performance over temperature : -40 to 100°C
 Supply current : 3mA (max)
 Power supply voltage : 10 to 20 V

Threshold input current : I_{FLH} = 8 mA (max)
 Switching time (t_{pLH} / t_{pHL}) : 200 ns (max)
 Common mode transient immunity :±10 kV/µs(min)
 Isolation voltage : 5000 Vrms(min)

UL Recognized :UL1577, File No.E67349

· Construction Mechanical Rating

	7.62-mm pitch standard type	10.16-mm pitch TLPXXXF type
Creepage Distance Clearance Insulation Thickness	7.0 mm (min) 7.0 mm (min) 0.4 mm (min)	8.0 mm (min) 8.0 mm (min) 0.4 mm (min)

Option (D4)

TÜV approved : EN60747-5-2

Certificate No. R50033433

Maximum operating insulation voltage : 890 Vpk Highest permissible over voltage : 8000 Vpk

(Note) When a EN60747-5-2 approved type is needed, please designate the "Option(D4)"

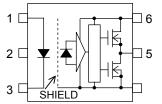
Truth Table

Input	LED	Tr1	Tr2	Output
Н	ON	ON	OFF	Н
L	OFF	OFF	ON	L

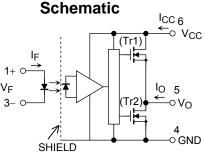
Unit in mm 4.58±0.25 6 5 4 1 2 3 000 7.62±0.25 1.27±0.2 1.25±0.25 9.7±0.3 11-5J1 TOSHIBA 11-5J1

Weight: 0.26 g (typ.)

Pin Configuration (Top View)



- 1: ANODE 2: NC
- 3: CATHODE
- 4: GND
- 5: VO (OUTPUT)
- 6: V_{CC}



A 0.1 μF bypass capacitor must be connected between pins 6 and 4. (See Note 6.)

TLP705



Absolute Maximum Ratings (Ta = 25°C)

	Characteristics	Symbol	Rating	Unit	
	Forward current		lF	20	mA
	Forward current derating (Ta ≥ 85°C)		ΔI _F /ΔTa	-0.54	mA/°C
LED	Peak transient forward current	(Note 1)	IFP	1	Α
	Reverse voltage		V _R	5	V
	Junction temperature		Tj	125	°C
	"H" peak output current	(Note 2)	I _{OPH}	-0.45	Α
o	"L" peak output current	(Note 2)	I _{OPL}	0.45	Α
Detector	Output voltage		VO	25	V
ă	Supply voltage		V _{CC}	25	V
	Junction temperature		Tj	125	°C
Oper	rating frequency	(Note 3)	f	250	kHz
Storage temperature range			T _{stg}	-55 to 125	°C
Operating temperature range			T _{opr}	-40 to 100	°C
Lead soldering temperature (10 s) (Note 4)		T _{sol}	260	°C	
Isola	tion voltage (AC, 1 minute, R.H. ≤ 60%)	(Note 5)	BVS	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Pulse width $P_W \le 1 \mu s$, 300 pps
- Note 2: Exponential waveform pulse width $P_W \le 10 \mu s$, $f \le 15 kHz$
- Note 3: Exponential waveform Ioph \leq -0.25 A (\leq 80 ns) , IopL \leq +0.25 A (\leq 80 ns) ,Ta =100 °C
- Note 4: It is effective soldering area of Lead .
- Note 5: Device considered a two terminal device: pins 1, 2 and 3 shorted together, and pins 4, 5 and 6 shorted together.
- Note 6: A ceramic capacitor $(0.1 \ \mu F)$ should be connected from pin 6 to pin 4 to stabilize the operation of the high gain linear amplifier. Failure to provide the bypassing may impair the switching property. The total lead length between capacitor and coupler should not exceed 1 cm.

Recommended Operating Conditions

Characteristics		Symbol	Min	Тур.	Max	Unit
Input current, ON	(Note 7)	I _{F (ON)}	10	_	15	mA
Input voltage, OFF		V _F (OFF)	0		0.8	V
Supply voltage		V _{CC}	10		20	V
Peak output current		I _{OPH} / I _{OPL}		_	± 0.15	Α
Operating temperature		T _{opr}	- 40	_	100	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Note 7: Input signal rise time (fall time) $< 0.5 \mu s$.

Note 8: If the rising slope of the supply voltage (VCC) for the detector is steep, stable operation of the internal circuits cannot be guaranteed.

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Be sure to set $3.0V/\mu s$ or less for a rising slope of the VCC.

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Electrical Characteristics (Ta = -40 to 100°C, unless otherwise specified)

Characteristic	S	Symbol	Test Circuit	Test Condition		Min	Тур.*	Max	Unit
Forward voltage		V _F	_	I _F = 10 mA, Ta = 2	25°C	_	1.6	1.8	V
Temperature coefficient o voltage	f forward	ΔV _F /ΔTa	_	I _F = 10 mA		_	-2.0	_	mV/°C
Input reverse current		I _R	_	V _R = 5 V, Ta = 25	°C	_	_	10	μА
Input capacitance		C _T	_	V = 0 V, $f = 1 MH$	z,Ta = 25°C	_	45	_	pF
	"H" Level	I _{OPH1}	1	V _{CC} = 15 V	$V_{6-5} = 4 V$	-0.15	-0.35	_	- A
Output current	II Level	I _{OPH2}	ı	1 10 1	V ₆₋₅ = 10 V	-0.3	-0.6	_	
(Note 9)	"L" Level	I _{OPL1}	2	V _{CC} = 15 V	$V_{5-4} = 2 V$	0.15	0.36	_	
	L Level	I _{OPL2}	2	$I_F = 0 \text{ mA}$	V ₅₋₄ = 10 V	0.3	0.62	_	
Output voltage	"H" Level	V _{OH}	3	- V _{CC} = 10 V	$I_O = -100 \text{ mA},$ $I_F = 10 \text{ mA}$	6.0	8.5	_	· V
Output voltage	"L" Level	V _{OL}	4		$I_O = 100 \text{ mA}, V_F = 0.8 \text{ V}$	_	0.4	1.0	
Supply ourrant	"H" Level	Icch	5	V _{CC} = 10 to 20 V	I _F = 10 mA	_	2.0	3.0	mA
Supply current	"L" Level	ICCL	6	V _O open	I _F = 0 mA	_	2.0	3.0	
Threshold input current	$L\toH$	I _{FLH}		V _{CC} = 15 V, V _O > 1 V		_	2.5	8	mA
Threshold input voltage	$H \rightarrow L$	V _{FHL}	_	V _{CC} = 15 V, V _O < 1 V		0.8	_	_	V
Supply voltage		V _{CC}	_	_	-	10	_	20	V

^{*:} All typical values are at Ta = 25°C

Note 9: Duration of I_O time \leq 50 μ s

Note10: This product is more sensitive than the conventional product to static electricity (ESD) because of a lowest power consumption design.

General precaution to static electricity (ESD) is necessary for handling this component.

Isolation Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance input to output	CS	V = 0 V, f = 1MHz (Note 5)	_	1.0	1	pF
Isolation resistance	R _S	R.H. ≤ 60%,V _S = 500V (Note 5)	1×10 ¹²	10 ¹⁴	ı	Ω
	BVS	AC, 1 minute	5000	1	ı	Vrms
Isolation voltage		AC, 1 second, in oil	_	10000	1	VIIIIS
		DC,1 minute,in oil	_	10000	_	Vdc

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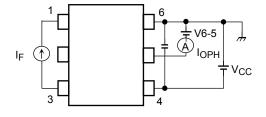
Switching Characteristics (Ta = -40 to 100° C, unless otherwise specified)

Characteristics		Symbol	Test Circuit	Test	Test Condition		Typ.*	Max	Unit					
Propagation delay time	$L \rightarrow H$	t _{pLH}		$V_{CC} = 20 \text{ V}$ $R_g = 30 \Omega$ $G_g = 1 \text{ nF}$	Ta= 25°C I _F = 0→10 mA	70	95	170						
Tropagation delay time	$H \rightarrow L$	t _{pHL}			Ta= 25 $^{\circ}$ C I _F = 10 \rightarrow 0 mA	70	105	170						
	$L \rightarrow H$	t _{pLH}			Ta= -40 to 100°C $I_F = 0 \rightarrow 10 \text{ mA}$	50	_	200						
Propagation delay time	$H \rightarrow L$	t _{pHL}	7		Ta= -40 to100°C I _F = 10→0 mA	50	_	200						
Propagation delay skew	(Note11)	tpsk		,	,	,	,	,		f=250kHz Duty Cycle =50%	Ta= -40 to100°C I _F = 10 mA	-90	_	90
Switching time dispersion between ON and OFF		t _{pHL} -t _{pLH}			Ta= -40 to100°C I _F = 10 mA	-65	_	65						
Output rise time (10-90%)		t _r			$I_F = 0 \rightarrow 10 \text{ mA}$	_	_	_						
Output fall time (90-10%)		t _f			$I_F = 10 \rightarrow 0 \text{ mA}$	_	_	_						
Common mode transient i at high level output	mmunity	CM _H	۰	V _{CM} = 1000Vp-p	I _F = 10 mA V _{O (min)} = 16 V	-10000	_	_	Mus					
Common mode transient immunity at low level output		CML	8	$V_{CC} = 20 \text{ V}$ $Ta = 25^{\circ}C$	I _F = 0 mA V _{O (max)} = 1 V	10000	_		V/μs					

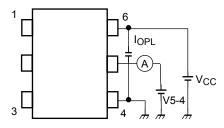
^{*:} All typical values are at $Ta = 25^{\circ}C$

Note 11: Propagation delay difference between any two parts.

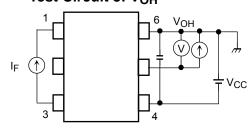
Test Circuit 1: I_{OPH}



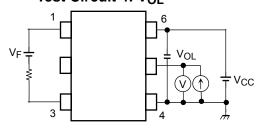
Test Circuit 2: I_{OPL}



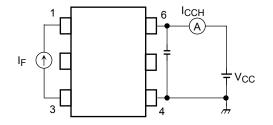
Test Circuit 3: V_{OH}



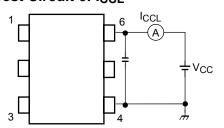
Test Circuit 4: V_{OL}



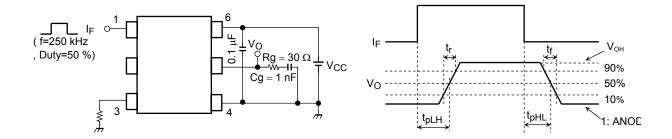
Test Circuit 5: I_{CCH}



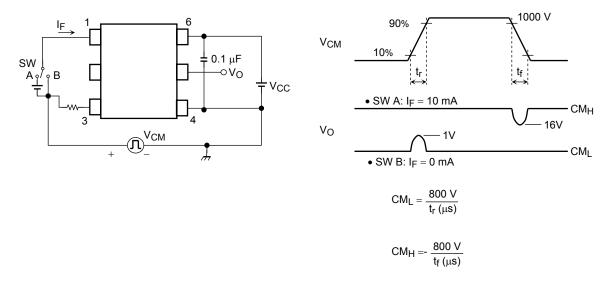
Test Circuit 6: I_{CCL}



Test Circuit 7: tplн, tpнL, tr, tf, PWD



Test Circuit 8: СМн, СМL



 CM_{L} (CM_H) is the maximum rate of rise (fall) of the common mode voltage that can be sustained with the output voltage in the low (high) state.

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